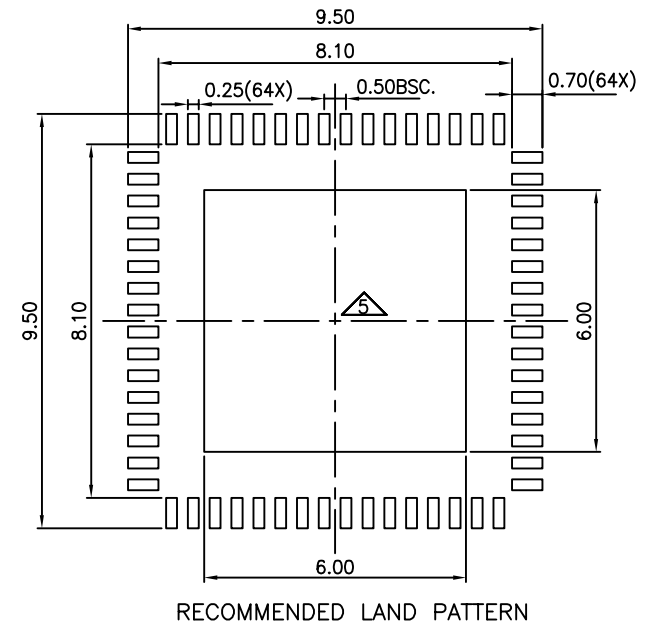
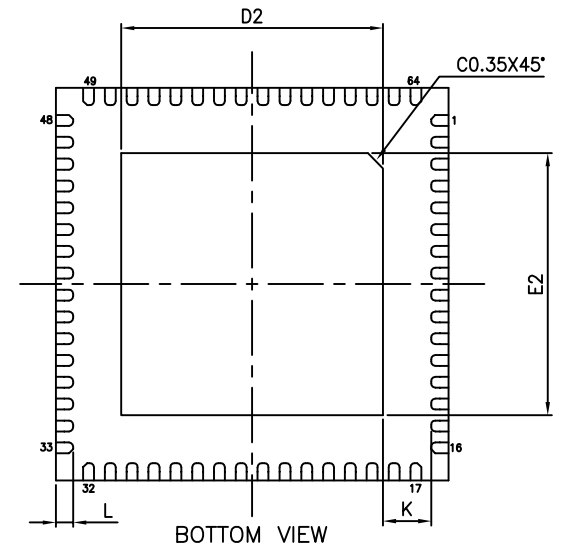
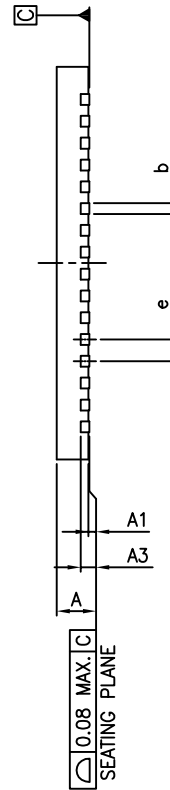


| SYMBOLS | MIN. | NOM. | MAX. |
|---------|------------|------|------|
| A | 0.80 | 0.85 | 0.90 |
| A1 | 0.00 | 0.02 | 0.05 |
| A3 | 0.203 REF. | | |
| b | 0.18 | 0.25 | 0.30 |
| D | 8.90 | 9.00 | 9.10 |
| E | 8.90 | 9.00 | 9.10 |
| e | 0.50 BSC. | | |
| K | 1.10 REF. | | |
| D2 | 5.95 | 6.00 | 6.05 |
| E2 | 5.95 | 6.00 | 6.05 |
| L | 0.35 | 0.40 | 0.45 |



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED)

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ENABLING SERIAL CONNECTIVITY

DATE: 05/18/18

DESCRIPTION: 64-Contact, Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZD (ZD64)

DOCUMENT CONTROL #: PD-2036

REVISION: D